

# **Notice of References Cited**

Application/Control No.  
09/667,770

Applicant(s)/Patent Under  
Reexamination  
KOMINO ET AL.

Examiner  
Rudy Zervigon

Art Unit  
1763

Page 1 of 1

## **U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification	
	A	US-6214162	04-2001	Koshimizu	156	345
	B	US-6095083	08-2000	Rice et al	118	7231
	C	US-6048434	04-2000	Tamura et al	156	345
	D	US-5961774	10-1999	Tamura et al	156	345
	E	US-5792304	08-1998	Tamura et al	156	345
	F	US-5376213	12-1994	Ueda et al	29	25.01
	G	US-5169407	12-1992	Mase et al	118	725
	H	US-5062386	11-1991	Christensen		
	I	US-				
	J	US-				
	K	US-				
	L	US-				
	M	US-				

## **FOREIGN PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification	
	N						
	O						
	P						
	Q						
	R						
	S						
	T						

## **NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)					
	U	J.D.R. Write, et al, "Low temperature etch chuck: Modeling and experimental results of heat transfer and wafer temperature". J.Vac. Sci. Technol. A 10(4), Jul/Aug, 1992. pp.1065-1070					
	V	CRC Handbook of Chemistry and Physics, Robert C. Weast (Ed.), 63rd Ed. 1982-1983; P. E-9					
	W						
	X						

A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a))  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.